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## Special Issue on Solid Mechanics and Its Applications

### Call for Papers

Solid mechanics is the branch of physics and mathematics that concerns the behavior of solid matter under external actions. It has been advanced by participating in major inventions throughout history, such as buildings, ships, automobiles, railways, petroleum refineries, engines, airplanes, nuclear reactors, composite materials, computers, and medical implants. The goal of this special issue is to provide a platform for scientists and academicians all over the world to promote, share, and discuss various new issues and developments in this area of **solid mechanics and its applications**.

In this special issue, we invite front-line researchers and authors to submit original research and review articles that explore **solid mechanics and its applications**. In this special issue, potential topics include, but are not limited to:

- Stress, strain and mechanical properties
- Beams, columns, plates, and shells
- Stress concentrations and fracture
- Stresses and strains in structural elements
- Static equilibrium, force resultants, support conditions
- Analysis of determinate planar structures
- Methods of structural mechanics
- Mechanical properties of coated fabrics
- Failure criteria for composite materials
- Fracture mechanics; fracture under dynamic loading,
- Solid mechanics and its applications

Authors should read over the journal's [For Authors](#) carefully before submission. Prospective authors should submit an electronic copy of their complete manuscript through the journal's [Paper Submission System](#).

Please kindly specify the “**Special Issue**” under your manuscript title. The research field “**Special Issue – Solid Mechanics and Its Applications**” should be selected during your submission.

Special Issue timetable:

Submission Deadline	September 29th, 2021
Publication Date	November 2021



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